L Number	Hits	Search Text	DB	Time stamp
11	0	6124769.pn and alumina and ruthenium	USPAT; US-PGPUB;	2004/05/20 13:56
17	1	"3353124".PN.	IBM_TDB USPAT	2004/05/20
19	6	(29/612).ccls. and ((thermistor near chip) or (chip near resistor)) and glass	USPAT; US-PGPUB;	14:12 2004/05/20 15:25
25	1	(333/172).ccls. and ((thermistor near chip) or (chip near resistor)) and (alumina adj substrate) and ruthenium and	IBM_TDB USPAT; US-PGPUB; IBM_TDB	2004/05/20 15:29
-	608	stack\$3 29/611.ccls.	USPAT; US-PGPUB;	2003/06/04 19:12
_	586	29/\$.ccls. and substrate and ((etch or etched or etching) with foil)	IBM_TDB USPAT; US-PGPUB; IBM TDB	2003/06/04 15:56
-	0	29/\$.ccls. and (photoresistive with substrate) and ((etch or etched or etching) with foil)	USPAT; US-PGPUB; IBM TDB	2003/06/04 15:56
_	. 4	29/\$.ccls. and (photoresistive and substrate) and ((etch or etched or etching) with foil)	USPAT; US-PGPUB; IBM TDB	2003/06/04 15:57
-	11	29/\$.ccls. and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching) with	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:03
_	17	layer or coat or coating)) and substrate and ((etch or etched or etching) and	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:11
-	100	layer or coat or coating)) and substrate and ((etch or etched or etching) and	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:12
_	48	foil) ((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or	USPAT; US-PGPUB; IBM_TDB	2003/06/04 19:49
-	7	etched or etching) and foil) ("4336320" "5466963" "5849355" "5872038" "5935642" "5960270" "5994997").PN.	USPAT	2003/06/04 16:19
	8	("4479890" "4610810" "4870746" "5162144" "5260170" "5338567" "5347258" "5792594").PN.	USPAT	2003/06/04 16:30
	28	((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and (etch or etched or etching) and foil and width	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:42
_	28	((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and (etch or etched or etching) and foil with (thick	USPAT; US-PGPUB; IBM_TDB	2003/06/04
	28	(resistive adj (film or layer or coat or coating)) and substrate and (etch or etched or etching) and (foil with (thick	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:48
_	32	or thickness or width)) ((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching or polishing) with foil)	USPAT; US-PGPUB; IBM_TDB	2003/06/04 19:42

_	17	("2945180" "3808576" "3813631"	USPAT	2003/06/04
		"4174513" "4737747" "4888574"		17:03
		"4892776" "5336391" "5422313"		
		"5483217" "5756971" "5864281"		
		"5907273" "5994997" "6141870"		
		"6232042" "6248612").PN.		
-	14	(29/611,10.1,620).ccls. and substrate and	USPAT;	2003/06/05
		((etch or etched or etching) with foil)	US-PGPUB;	09:15
		and resistor	IBM TDB	
_	38	(338/306-309).ccls. and substrate and	USPAT;	2003/06/05
		((etch or etched or etching) with foil)	US-PGPUB;	09:16
ŀ		and resistor	IBM TDB	
-	3	(338/306-309).ccls. and substrate and	USPAT;	2003/06/05
		((etch or etched or etching) with foil)	US-PGPUB;	09:18
1		and ((method or processor assembling or	IBM_TDB	
		making or manufacturing or step) adj		
		resistor)		
-	79	(430/313,315,324).ccls. and substrate and	USPAT;	2003/06/05
		((etch or etched or etching) with foil)	US-PGPUB; .	09:19
1			IBM_TDB	
-	13	(430/313,315,324).ccls. and substrate and	USPAT;	2003/06/05
		((etch or etched or etching) with foil)	US-PGPUB;	09:19
		and resistor	IBM_TDB	0000105155
-	1	(438/462,977).ccls. and substrate and	USPAT;	2003/06/05
		(etch or etched or etching) and foil and	US-PGPUB;	09:20
		resistor	IBM_TDB	2002/06/05
-	18	3669022.URPN.	USPAT	2003/06/05
	_	C020040 UDDV	HCDAM	10:42
-	1	6232042.URPN.	USPAT	2003/06/05
		510100	110 D D M .	10:46
-	1	6194990.pn.	USPAT;	2003/06/05
			US-PGPUB;	11:20
		(#2710500# #4706564# #4000574#	IBM_TDB	2002/06/05
-	11	("3719508" "4786564" "4888574"	USPAT	2003/06/05 10:48
		"4892776" "5053318" "5336391" "5347258" "5403672" "5560812"		10.40
		"5679498" "6171921").PN.		-
	11	4297670.URPN.	USPAT	2003/06/05
-	11	4237670.UREN.	OSERI	10:50
_	12	("2945180" "3808576" "3813631"	USPAT	2003/06/05
-	12	"4174513" "4888574" "4892776"	001111	10:51
	1	"5336391" "5422313" "5483217"		
		"5756971" "5864281" "5907273").PN.		
_	3	6194990.URPN.	USPAT	2003/06/05
		013 1330 . O. C		10:52
_	11	laminated adj resistor	USPAT;	2003/06/05
			US-PGPUB;	11:21
			IBM TDB	
-	1988	chip adj resistor	USPAT;	2003/06/05
			US-PGPUB;	11:30
	1		IBM TDB	
-	570	(chip adj resistor) and glass	USPAT;	2003/06/05
	1		US-PGPUB;	11:22
			IBM_TDB	
-	328	(chip adj resistor) and glass and	USPĀT;	2003/06/05
	1	terminal	US-PGPUB;	11:22
ŀ	1		IBM_TDB	
-	126	(chip adj resistor) and glass and	USPĀT;	2003/06/05
		terminal and nickel	US-PGPUB;	11:23
	1		IBM_TDB	1
-	126		USPAT;	2003/06/05
		making or producing or steps) and (chip	US-PGPUB;	11:24
		adj resistor) and glass and terminal and	IBM_TDB	
		nickel		0000465465
-	11		USPAT;	2003/06/05
		making or producing or steps) adj (chip	US-PGPUB;	11:24
		adj resistor) and glass and terminal and	IBM_TDB	
	_	nickel	HCDAM	2002/06/05
-	5		USPAT	2003/06/05
		"5510594" "5680092").PN.	l	11:28

_	30	(29/610.1,620,621).ccls. and (chip adj resistor)	USPAT; US-PGPUB;	2003/06/05 11:39
_	10	4267634.URPN.	IBM_TDB USPAT	2003/06/05 11:36
-	5	(29/610.1,620,621).ccls. and (chip adj resistor) and multilayer	USPAT; US-PGPUB;	2003/06/05 11:40
_	11	(338/308,309,332).ccls. and (chip adj resistor) and multilayer	IBM_TDB USPAT; US-PGPUB;	2003/06/05 11:41
_	13	5170146.URPN.	IBM_TDB USPAT	2003/06/05
_	10	5287083.URPN.	USPAT	11:42 2003/06/05
_	1	4267634.pn. and glass	USPAT; US-PGPUB;	11:47 2003/06/05 13:32
_	10	4267634.URPN.	IBM_TDB USPAT	2003/06/05
_	0	multilayered adj resistor	USPAT; US-PGPUB;	13:12 2003/06/05 13:16
-	8	multi-layered near resistor	IBM_TDB USPAT; US-PGPUB;	2003/06/05 13:20
-	32723	ceramic near glass	IBM_TDB USPAT; US-PGPUB;	2003/06/05 13:20
_	3649	(ceramic near glass) and resistor	IBM_TDB USPAT; US-PGPUB;	2003/06/05 13:21
-	81	(ceramic near glass) and (chip adj resistor)	IBM_TDB USPAT; US-PGPUB;	2003/06/05 13:21
_	0	4267634.pn. and nickel	IBM_TDB USPAT; US-PGPUB;	2003/06/05 13:36
-	3612	nickel with melting	IBM_TDB USPAT; US-PGPUB;	2003/06/05 13:37
_	2226	nickel with (melting adj (point or temperature))	IBM_TDB USPAT; US-PGPUB; IBM TDB	2003/06/05 13:38
_	314	nickel near (melting adj (point or temperature))	USPAT; US-PGPUB; IBM TDB	2003/06/05 13:39
_	17	nickel near (melting adj (point or temperature)) and resistor	USPAT; US-PGPUB; IBM TDB	2003/06/05 13:50
-	9	palladium near (melting adj (point or temperature)) and resistor	USPAT; US-PGPUB;	2003/06/05 13:51
_	0	(29/619).ccls. and (chip adj resistor) and multilayer	IBM_TDB USPAT; US-PGPUB;	2003/06/05 15:03
-	17	(29/611,610.1,619,620,621).ccls. and substrate and ((etch or etched or	IBM_TDB USPAT; US-PGPUB;	2003/06/05 15:05
-	15	etching) with foil) and resistor (29/610.1,619,620,621).ccls. and substrate and ((etch or etched or	IBM_TDB USPAT; US-PGPUB;	2003/06/05 15:08
-	31	etching) with foil) and resistor (174/260).ccls. and substrate and ((etch or etched or etching) with foil) and	IBM_TDB USPAT; US-PGPUB;	2003/06/05 15:08
_	19	resistor	IBM_TDB USPAT; US-PGPUB;	2003/06/05 15:09
_	2	resistor and multilayer\$3	IBM_TDB USPAT; US-PGPUB;	2003/11/12 17:20
			IBM_TDB	

			r	
-	15	"5488348"	USPAT;	2004/05/18
			US-PGPUB;	18:05
	İ		IBM_TDB	
-	1	5488348.pn.	USPAT;	2004/05/18
			US-PGPUB;	18:11
			IBM_TDB	
-	0	(95/31816).CCLS.	EPO_	2004/05/18
	,			18:12
_	0	(WO95/31816).CCLS.	EPO	2004/05/18
	_	(18:12
_	0	("WO9531816").PN.	EPO	2004/05/18
		(1103031010) 11111	12.0	18:12
_	0	(("5303115") or ("3775725") or	EPO	2004/05/19
_		("4924074")).PN.	EFO.	13:55
	6		USPAT;	2004/05/19
-				13:55
		("4924074")).PN.	US-PGPUB;	13:33
			DERWENT;	
	_		IBM_TDB	
-	3	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2004/05/19
		("4924074")).PN.	US-PGPUB;	13:55
			IBM TDB	
-	1	("6606023").PN.	USPAT;	2004/05/19
			US-PGPUB;	14:32
			IBM TDB	
_	o	("6311390").PN.	EPO	2004/05/19
		,		15:27
_	1	("6311390").PN.	USPAT;	2004/05/19
	_	(0311990 /:IN:	US-PGPUB;	17:16
	ļ		IBM TDB	17.10
	_	/#5400240# #5402266# #602000#	_	2004/05/10
-	5	("5488348" "5493266" "6020808"	USPAT	2004/05/19
	_ :	"6040755" "6157289").PN.		15:29
-	5	(thermistor adj strip) and glass	USPAT;	2004/05/19
	i i		US-PGPUB;	15:37
			IBM_TDB	
-	48	(thermistor adj chip) and glass	USPAT;	2004/05/19
			US-PGPUB;	15:40
			IBM TDB	
_	13	(thermistor adj chip) and glass and	USPAT;	2004/05/19
		alumina	US-PGPUB;	15:40
			IBM TDB	
_	1	(thermistor adj chip) and glass and	USPAT;	2004/05/19
		alumina and ruthenium	US-PGPUB;	16:12
		aramina and raciferran	IBM TDB	10.12
_	55	(/thormistor add ship) or (ship add	USPAT;	2004/05/19
_	35	((thermistor adj chip) or (chip adj resistor)) and glass and alumina and	US-PGPUB;	16:29
			IBM TDB	10.29
	1.0	ruthenium		2004/05/10
-	12	((thermistor adj chip) or (chip adj	USPAT;	2004/05/19
	1	resistor)) and glass and alumina and	US-PGPUB;	16:33
		ruthenium and stack\$3	IBM_TDB	1 (
-	6	((thermistor adj chip) or (chip adj	USPAT;	2004/05/19
	1	resistor)) and glass and (alumina adj	US-PGPUB;	16:34
		substrate) and ruthenium and stack\$3	IBM_TDB	
-	1	6311390.pn. and glass	USPAT;	2004/05/19
1			US-PGPUB;	17:16
	1		IBM TDB	
-	0	6311390.pn. and glass and alumina	USPAT;	2004/05/19
			US-PGPUB;	17:16
			IBM TDB	
_	0	6311390.pn. and glass and ruthenium	USPAT;	2004/05/19
	1		US-PGPUB;	17:17
1			IBM TDB	- / /
_	1	"3353124".PN.	USPAT	2004/05/19
-	1	3333124 .FN.	USPAI	2004/05/19
	.	("(C)(C)7() PN	Hansa	17:52
-	1	("6362723").PN.	USPAT;	2004/05/19
	[US-PGPUB;	18:07
			IBM_TDB	
-	6		USPAT;	2004/05/19
		resistor)) and glass and (alumina adj	US-PGPUB;	18:13
	<u> </u>	substrate) and ruthenium and stack\$3	IBM_TDB	

_	914	((thermistor near chip) or (chip near	USPAT;	2004/05/19
		resistor)) and glass	US-PGPUB;	18:20
		-	IBM_TDB	ĺ
-	121	((thermistor near chip) or (chip near	USPAT;	2004/05/19
		resistor)) and glass and (alumina adj	US-PGPUB;	18:12
		substrate)	IBM_TDB	
-	33	((thermistor near chip) or (chip near	USPAT;	2004/05/19
		resistor)) and glass and (alumina adj	US-PGPUB;	18:25
		substrate) and ruthenium	IBM_TDB	
-	77	((thermistor near chip) or (chip near	USPAT;	2004/05/19
		resistor)) and (glass adj substrate)	US-PGPUB;	18:21
			IBM_TDB	
-	20	((thermistor near chip) or (chip near	USPAT;	2004/05/19
		resistor)) and glass and (alumina adj	US-PGPUB;	18:25
		substrate) and ruthenium and plat\$3	IBM_TDB	
-	6	1 , ,	USPAT;	2004/05/19
		resistor)) and glass and (alumina adj	US-PGPUB;	18:26
		substrate) and ruthenium and (nickel near	IBM_TDB	
		plat\$3)		